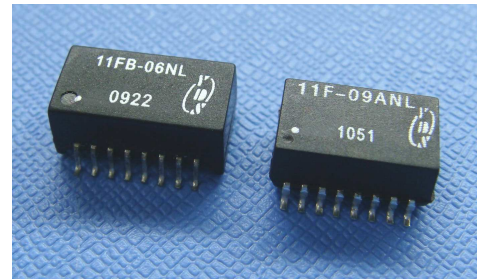




FEATURES

- Meet IEEE 802.3 and ANSI X3.263 standards including 350 uH OCL with 8mA Bias
- Designed to withstand IR reflow temperatures up to 235°C
- Compact footprint use in the most space restrictive applications
- Recognized by UL 1950.

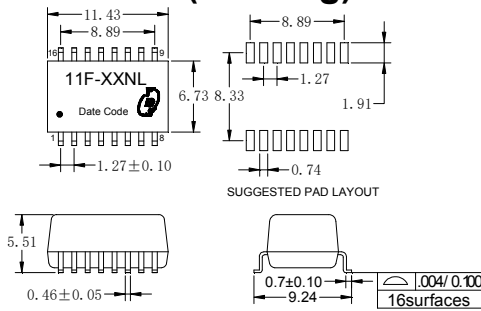


ELECTRICAL SPECIFICATIONS @25°C -Operating temperature -40°C TO 85°C

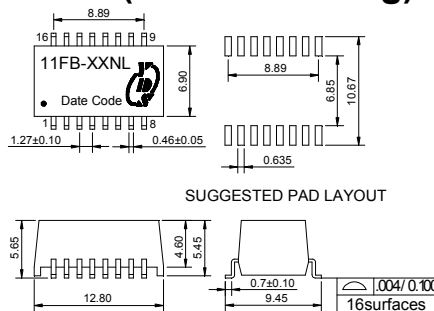
Part Number	Turns Ratio (±5%)		Insertion Loss (dB MAX)	Return Loss (dB TYP)			Differential to Common Mode Rejection (dB MIN)			Crosstalk (dB TYP)			Hipot V _{rms} MIN
	TX	RX		30 MHz	60 MHz	80 MHz	30 MHz	50 MHz	100 MHz	30 MHz	60 MHz	100 MHz	
11F(B)-05	1CT:1CT	1CT:1CT	-1.1	-20	-14	-11.5	-42	-37	-33	-45	-40	-35	1500
11F(B)-06	1.25CT:1CT	1CT:1CT	-1.1	-20	-14	-11.5	-42	-37	-33	-45	-40	-35	1500

MECHANICAL

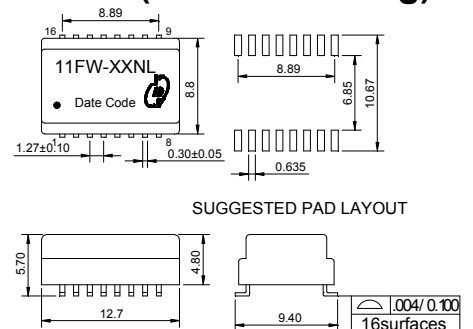
11F(Molding)



11FB(Bottom Potting)

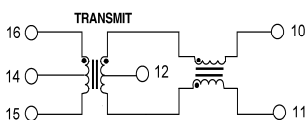


11FW(Bottom Potting)

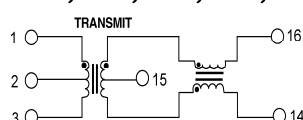


SCHEMATICS

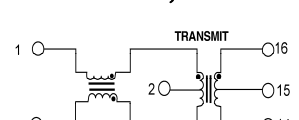
11F-01



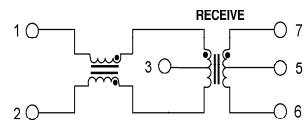
11F-05, 06, 07, 08, 11



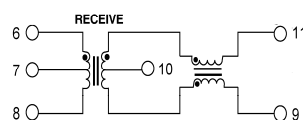
11F-09, 12



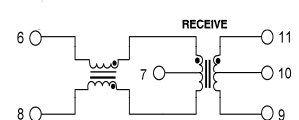
RECEIVE



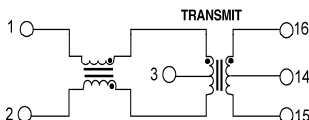
RECEIVE



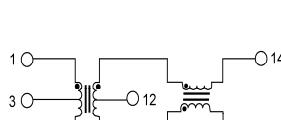
RECEIVE



11F-10



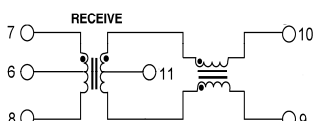
11F-16



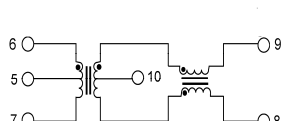
11F-17



RECEIVE



RECEIVE



RECEIVE

